2309410-1 V ACTIVE

DDR4 DIMM

TE Internal #: 2309410-1

SO DIMM Sockets, Small Outline (SO), Stack Height .205 in [5.2 mm], Right Angle Module Orientation, 200 / 260 Position, DDR4

DIMM

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Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets > DDR4 SO DIMM Sockets



DRAM Type: Small Outline (SO) Stack Height: **5.2 mm [.205 in]** Module Orientation: Right Angle Connector System: Cable-to-Board Number of Positions: 200, 260

All DDR4 SO DIMM Sockets (39)

Features

Product Type Features	
DRAM Type	Small Outline (SO)
Connector System	Cable-to-Board
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Number of Keys	1
Number of Rows	2
Module Orientation	Right Angle
Number of Positions	200, 260
Electrical Characteristics	
DRAM Voltage	1.2 V
Signal Characteristics	
SGRAM Voltage	1.2 V
Body Features	
Ejector Location	Both Ends
Retention Post Material	Copper Alloy



Latch Material High Temperature Thermoplastic Retention Post Location Both Ends Fjedon Type Looking Connector Profile Low Contact Features Memory Socket Type Memory Card Contact Underplating Material Nickel PCB Contact Termination Area Plating Material Gold Flash Contact Base Material Copper Alloy Contact Mating Area Plating Material Gold Flash Contact Mating Area Plating Material Gold Flash Contact Mating Area Plating Material Gold Flash Contact Mating Alignment Type Cam In Mechanical Attachment Mating Alignment Type Reverse Keying PCB Mounting Style Surface Mount PCB Mount Retention Type Solder Peg Connector Mounting Type Board Mount Housing Features Llousing Material Lligh Temperature Thermoplastic Llousing Color Black Centerline (Pitch) 5.5 mm, 3.3 mm (02 in) (129 in) Dimensions Stack Height S.2 mm (205 in) Row-to-Row Spacing Sand Sand Sand Sand Sand Sand Sand Sand		
Connector Profile Contact Features Memory Sacket Type Contact Underplating Material PCB Contact Termination Area Plating Material Contact Base Material Contact Mating Area Plating Material Contact Mating Area Plating Material Gold Flash Contact Current Rating (Max) SA Termination Features Insertion Style Cam-In Mechanical Attachment Mating Alignment Type Reverse Keying PCB Mounting Style Surface Mount PCB Mount Retention PCB Mount Retention Type Solder Peg Connector Mounting Type Housing Features Housing Material High Temperature Thermoplastic Housing Color Black Centerline (Pitch) Smm, 3.3 mm, 02 inj[,129 inj] Dimensions Stack Height S2 mm, 329 inj Usage Conditions Operating Temperature Range	Latch Material	High Temperature Thermoplastic
Contact Features Memory Socket Type Contact Underplating Material PCB Contact Termination Area Plating Material Contact Base Material Contact Base Material Contact Mating Area Plating Material Contact Current Rating (Max) SA Termination Features Insertion Style Cam-In Mechanical Attachment Mating Alignment Type Reverse Keying PCB Mounting Style Surface Mount PCB Mount Retention PCB Mount Retention Type Connector Mounting Type Board Mount Housing Features Housing Material High Temperature Thermoplastic Itousing Color Black Centerline (Pitch) S mm, 3.3 mm[.02 in][.129 in] Dimensions Stack Height S.2 mm[.205 in] Row-to-Row Spacing Usage Conditions Coperating Temperature Range -55 - 85 °CI-67 - 185 °FI]	Retention Post Location	Both Ends
Memory Socket Type Memory Card Contact Underplating Material Nickel PCB Contact Termination Area Plating Material Gold Flash Contact Base Material Copper Alloy Contact Mating Area Plating Material Gold Flash Contact Current Rating (Max) .5 A Termination Features Insertion Style Cam In Mechanical Attachment Mating Alignment Type Reverse Keying PCB Mounting Style Surface Mount PCB Mount Retention Type Solder Peg Connector Mounting Type Board Mount Housing Features Housing Material High Temperature Thermoplastic Housing Material High Temperature Thermoplastic Housing Color Black Centerline (Pitch) .5 mm, 3.3 mm[.02 in][.129 in] Dimensions Stack Height S.2 mm[.205 in] Row to Row Spacing 8.2 mm[.322 in] Usage Conditions Operating Temperature Range 55 - 85 °C[67 - 185 °F]	Ejector Type	Locking
Memory Socket Type Contact Underplating Material PCB Contact Termination Area Plating Material Contact Base Material Contact Base Material Contact Base Material Contact Mating Area Plating Material Contact Current Rating (Max) J.5 A Termination Features Insertion Style Cam-In Mechanical Attachment Mating Alignment Type Reverse Keying PCB Mounting Style Surface Mount PCB Mount Retention With PCB Mount Retention Type Solder Peg Connector Mounting Type Board Mount Housing Features Ilousing Material Housing Color Black Centerline (Pitch) Dimensions Stack Height S.2 mm[.205 in] Row-to-Row Spacing Usage Conditions Operating Temperature Range -55 –85 °C[-67 – 185 °F]	Connector Profile	Low
Contact Underplating Material PCB Contact Termination Area Plating Material Contact Base Material Contact Base Material Contact Mating Area Plating Material Contact Mating Area Plating Material Contact Current Rating (Max) .5 A Termination Features Insertion Style Carn In Mechanical Attachment Mating Alignment Type Reverse Keying PCB Mounting Style Surface Mount PCB Mount Retention With PCB Mount Retention Type Solder Peg Connector Mounting Type Board Mount Housing Features Housing Material High Temperature Thermoplastic Housing Color Black Conterline (Pitch) Dimensions Stack Height 5.2 mm [.205 in] Row-to-Row Spacing 8.2 mm [.322 in] Usage Conditions Operating Temperature Range	Contact Features	
PCB Contact Termination Area Plating Material Contact Base Material Contact Mating Area Plating Material Contact Current Rating (Max) .5 A Termination Features Insertion Style Cam-In Mechanical Attachment Mating Alignment Type Reverse Keying PCB Mounting Style Surface Mount PCB Mount Retention With PCB Mount Retention Type Connector Mounting Type Board Mount Housing Features Housing Material High Temperature Thermoplastic Housing Color Black Centerline (Pitch) .5 mm, 3.3 mm[.02 in][.129 in] Dimensions Stack Height S.2 mm[.205 in] Row-to-Row Spacing Usage Conditions Operating Temperature Range	Memory Socket Type	Memory Card
Contact Base Material Copper Alloy Contact Mating Area Plating Material Gold Flash Contact Current Rating (Max) .5 A Termination Features Insertion Style Cam In Mechanical Attachment Mating Alignment Type Reverse Keying PCB Mounting Style Surface Mount PCB Mount Retention PCB Mount Retention Type Solder Peg Connector Mounting Type Board Mount Housing Features Housing Material High Temperature Thermoplastic Housing Color Black Centerline (Pitch) .5 mm, 3.3 mm[.02 in][.129 in] Dimensions Stack Height 5.2 mm[.205 in] Row-to-Row Spacing 8.2 mm[.322 in] Usage Conditions Operating Temperature Range	Contact Underplating Material	Nickel
Contact Mating Area Plating Material Contact Current Rating (Max) Termination Features Insertion Style Cam-In Mechanical Attachment Mating Alignment Type Reverse Keying PCB Mounting Style Surface Mount PCB Mount Retention PCB Mount Retention Type Solder Peg Connector Mounting Type Board Mount Housing Features Housing Material High Temperature Thermoplastic Housing Color Black Centerline (Pitch) Dimensions Stack Height Solder Mount Solder Peg Solder	PCB Contact Termination Area Plating Material	Gold Flash
Contact Current Rating (Max) Termination Features Insertion Style Cam-In Mechanical Attachment Mating Alignment Type PCB Mounting Style PCB Mount Retention With PCB Mount Retention Type Connector Mounting Type Board Mount Housing Features Housing Material High Temperature Thermoplastic Housing Color Black Centerline (Pitch) 5.7 mm, 3.3 mm[.02 in][.129 in] Dimensions Stack Height Row-to-Row Spacing Usage Conditions Operating Temperature Range	Contact Base Material	Copper Alloy
Insertion Style Cam-In Mechanical Attachment Mating Alignment Type Reverse Keying PCB Mounting Style Surface Mount PCB Mount Retention With PCB Mount Retention Type Board Mount Housing Features Housing Material High Temperature Thermoplastic Housing Color Black Centerline (Pitch) .5 mm, 3.3 mm[.02 in][.129 in] Dimensions Stack Height 5.2 mm[.205 in] Row-to-Row Spacing 8.2 mm[.322 in] Usage Conditions Operating Temperature Range -55 – 85 °C[-67 – 185 °F]	Contact Mating Area Plating Material	Gold Flash
Insertion Style Mechanical Attachment Mating Alignment Type PCB Mounting Style PCB Mount Retention With PCB Mount Retention Type Solder Peg Connector Mounting Type Board Mount Housing Features Housing Material High Temperature Thermoplastic Housing Color Black Centerline (Pitch) Dimensions Stack Height Solder Peg	Contact Current Rating (Max)	.5 A
Mechanical Attachment Mating Alignment Type Reverse Keying PCB Mounting Style Surface Mount PCB Mount Retention With PCB Mount Retention Type Solder Peg Connector Mounting Type Board Mount Housing Features High Temperature Thermoplastic Housing Color Black Centerline (Pitch) .5 mm, 3.3 mm[.02 in][.129 in] Dimensions Stack Height Stack Height 5.2 mm[.205 in] Row-to-Row Spacing 8.2 mm[.322 in] Usage Conditions Operating Temperature Range -55 – 85 °C[-67 – 185 °F]	Termination Features	
Mating Alignment Type PCB Mounting Style Surface Mount PCB Mount Retention With PCB Mount Retention Type Solder Peg Connector Mounting Type Board Mount Housing Features Housing Material High Temperature Thermoplastic Housing Color Black Centerline (Pitch) 5 mm, 3.3 mm[.02 in][.129 in] Dimensions Stack Height Row-to-Row Spacing Usage Conditions Operating Temperature Range -55 – 85 °C[-67 – 185 °F]	Insertion Style	Cam-In
PCB Mount Retention With PCB Mount Retention Type Solder Peg Connector Mounting Type Board Mount Housing Features Housing Material High Temperature Thermoplastic Housing Color Black Centerline (Pitch) .5 mm, 3.3 mm[.02 in][.129 in] Dimensions Stack Height 5.2 mm[.205 in] Row-to-Row Spacing 8.2 mm[.322 in] Usage Conditions Operating Temperature Range -55 - 85 °C[-67 - 185 °F]	Mechanical Attachment	
PCB Mount Retention PCB Mount Retention Type Solder Peg Connector Mounting Type Board Mount Housing Features Housing Material Housing Color Black Centerline (Pitch) Dimensions Stack Height Solder Peg Board Mount High Temperature Thermoplastic Black 5.5 mm, 3.3 mm[.02 in][.129 in] Dimensions Stack Height 5.2 mm[.205 in] Row-to-Row Spacing Usage Conditions Operating Temperature Range -55 – 85 °C[-67 – 185 °F]	Mating Alignment Type	Reverse Keying
PCB Mount Retention Type Connector Mounting Type Board Mount Housing Features Housing Material High Temperature Thermoplastic Housing Color Black Centerline (Pitch) 5 mm, 3.3 mm[.02 in][.129 in] Dimensions Stack Height 5.2 mm[.205 in] Row-to-Row Spacing Usage Conditions Operating Temperature Range -55 – 85 °C[-67 – 185 °F]	PCB Mounting Style	Surface Mount
Connector Mounting Type Board Mount Housing Features Housing Material High Temperature Thermoplastic Black Centerline (Pitch) Dimensions Stack Height 5.2 mm[.205 in] Row-to-Row Spacing 8.2 mm[.322 in] Usage Conditions Operating Temperature Range -55 – 85 °C[-67 – 185 °F]	PCB Mount Retention	With
Housing Features Housing Material High Temperature Thermoplastic Housing Color Black Centerline (Pitch) .5 mm, 3.3 mm[.02 in][.129 in] Dimensions Stack Height 5.2 mm[.205 in] Row-to-Row Spacing 8.2 mm[.322 in] Usage Conditions Operating Temperature Range -55 – 85 °C[-67 – 185 °F]	PCB Mount Retention Type	Solder Peg
Housing Material High Temperature Thermoplastic Housing Color Black Centerline (Pitch) .5 mm, 3.3 mm[.02 in][.129 in] Dimensions Stack Height 5.2 mm[.205 in] Row-to-Row Spacing 8.2 mm[.322 in] Usage Conditions Operating Temperature Range -55 – 85 °C[-67 – 185 °F]	Connector Mounting Type	Board Mount
Housing Color Centerline (Pitch) .5 mm, 3.3 mm[.02 in][.129 in] Dimensions Stack Height 5.2 mm[.205 in] Row-to-Row Spacing 8.2 mm[.322 in] Usage Conditions Operating Temperature Range -55 - 85 °C[-67 - 185 °F]	Housing Features	
Centerline (Pitch) .5 mm, 3.3 mm[.02 in][.129 in] Dimensions Stack Height 5.2 mm[.205 in] Row-to-Row Spacing 8.2 mm[.322 in] Usage Conditions Operating Temperature Range -55 – 85 °C[-67 – 185 °F]	Housing Material	High Temperature Thermoplastic
DimensionsStack Height5.2 mm[.205 in]Row-to-Row Spacing8.2 mm[.322 in]Usage ConditionsUsage ConditionsOperating Temperature Range-55 - 85 °C[-67 - 185 °F]	Housing Color	Black
Stack Height 5.2 mm[.205 in] Row-to-Row Spacing 8.2 mm[.322 in] Usage Conditions Operating Temperature Range -55 – 85 °C[-67 – 185 °F]	Centerline (Pitch)	.5 mm, 3.3 mm[.02 in][.129 in]
Row-to-Row Spacing Usage Conditions Operating Temperature Range 8.2 mm[.322 in] -55 – 85 °C[-67 – 185 °F]	Dimensions	
Usage Conditions Operating Temperature Range -55 – 85 °C[-67 – 185 °F]	Stack Height	5.2 mm[.205 in]
Operating Temperature Range -55 – 85 °C[-67 – 185 °F]	Row-to-Row Spacing	8.2 mm[.322 in]
	Usage Conditions	
Operation/Application	Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
	Operation/Application	
Circuit Application Power	Circuit Application	Power
Industry Standards		
UL Flammability Rating UL 94V-0		UL 94V-0



Packaging Features

Packaging Quantity	800
Packaging Method	Tape & Reel

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts





Also in the Series | DDR4 DIMM







Customers Also Bought



















Documents

Product Drawings DDR4 SODIMM 260P 5.2H RVS

English

CAD Files

3D PDF

3D



Customer View Model

ENG_CVM_CVM_2309410-1_1.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2309410-1_1.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2309410-1_1.3d_stp.zip

English

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Product Specifications

Application Specification

English